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**Part Number:** **0737827100**  
**Status:** **Active**  
**Overview:** HDM Backplane Connector System  
**Description:** HDM Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits, Stack Height 15.05mm

**Documents:**

<a href="#">3D Model</a>	<a href="#">Product Specification PS-73780-999-001 (PDF)</a>
<a href="#">3D Model (PDF)</a>	<a href="#">Packaging Specification PK-70873-1873-001 (PDF)</a>
<a href="#">Drawing (PDF)</a>	<a href="#">RoHS Certificate of Compliance (PDF)</a>

**Agency Certification**

CSA	LR19980
UL	E29179

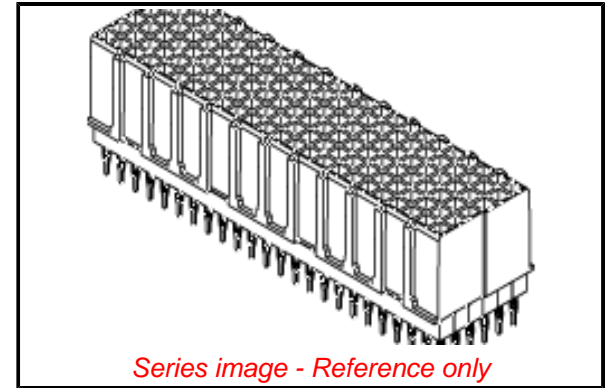
**General**

Product Family	Backplane Connectors
Series	<u>73782</u>
Application	Backplane, Mezzanine
Component Type	PCB Header
Overview	<u>HDM Backplane Connector System</u>
Product Name	HDM
UPC	800753000322

**Physical**

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	25.449/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole

**Electrical**



**EU ELV**

**Not Relevant**

**EU RoHS**

**Compliant**

**REACH SVHC**

Not Contained Per -  
D(2021)4569-DC (8  
July 2021)

**Halogen-Free**

**Status**

**Low-Halogen**

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

**China RoHS**

Green Image

Not Relevant

Not Contained

**Search Parts in this Series**

73782 Series

**Mates With**

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC

**Solder Process Data**

Duration at Max. Process Temperature (seconds)	005
Lead-free Process Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

**Material Info****Reference - Drawing Numbers**

Packaging Specification	PK-70873-1873-001
Product Specification	PS-73780-999-001
Sales Drawing	SD-73782-001-001, SD-73782-001-002

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